




PCN Number:	20240402000.1		PCN Date:	April 10, 2024																	
Title:	Qualify HFTF as an additional Assembly site for select devices																				
Customer Contact:	Change Management team		Dept:	Quality Services																	
Proposed 1st Ship Date:	July 09, 2024		Estimated Sample Availability:	May 10, 2024*																	
*Sample requests received after May 10, 2024 will not be supported.																					
Change Type:																					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material																
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process																
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Fab Site																
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Material																
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Process																
PCN Details																					
Description of Change:																					
Texas Instruments is pleased to announce the qualification of HFTF as an additional Assembly site for the list of devices shown below. Material differences between sites are as follows.																					
<table border="1"> <thead> <tr> <th></th> <th>UTL2</th> <th>ASESH</th> <th>HFTF</th> </tr> </thead> <tbody> <tr> <td>Wire type/diam</td> <td>1.3mil Au, 1.3mil Cu</td> <td>1.3mil Cu</td> <td>1.3mil Au</td> </tr> <tr> <td>Mount compound</td> <td>PZ0013</td> <td>EY1000063</td> <td>A-24</td> </tr> <tr> <td>Mold compound</td> <td>CZ0094</td> <td>EN2000515</td> <td>R-32</td> </tr> </tbody> </table>							UTL2	ASESH	HFTF	Wire type/diam	1.3mil Au, 1.3mil Cu	1.3mil Cu	1.3mil Au	Mount compound	PZ0013	EY1000063	A-24	Mold compound	CZ0094	EN2000515	R-32
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Package Outline Differences:																					
Existing (UTL2/ASESH)			New (HFTF)																		
Reason for Change:																					
Continuity of supply.																					
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):																					
None.																					
Impact on Environmental Ratings																					
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.																					

RoHS		REACH		Green Status		IEC 62474					
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change				
Changes to product identification resulting from this PCN:											
Assembly Site											
UTL2	Assembly Site Origin (22L)		ASO: NS2								
ASESH	Assembly Site Origin (22L)		ASO: ASH								
HFTF	Assembly Site Origin (22L)		ASO: HFT								
Sample product shipping label (not actual product label)											
   <div style="display: flex; justify-content: space-between;"> <div> <p>MADE IN: Malaysia 2DC: 24:</p> <table border="1"> <tr> <td>MSL 2 / 260C / 1 YEAR</td> <td>SEAL DT</td> </tr> <tr> <td>MSL 1 / 235C / UNLIM</td> <td>03 / 29 / 04</td> </tr> </table> <p>OPT: ITEM: LBL: 5A (L)T0:1750</p> </div> <div> <p>(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS</p> </div> </div>								MSL 2 / 260C / 1 YEAR	SEAL DT	MSL 1 / 235C / UNLIM	03 / 29 / 04
MSL 2 / 260C / 1 YEAR	SEAL DT										
MSL 1 / 235C / UNLIM	03 / 29 / 04										
Product Affected:											
TPS54240DGQR				TPS54260DGQR							

Qualification Report

Approve Date 25-March-2024

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TPS54260QDGRQ1	QBS Reference: LM5165XQDGRQ1	QBS Reference: TPS40210QDGRQ1	QBS Reference: SN105070EPNP	QBS Reference: TPS54260QDRCRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0		1/77/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0		-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	-	-		-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	1/45/0	-	-		-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-		-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	3/231/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	3/2400/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-		-
PD	C4	Physical Dimensions	Cpk>1.67	-	3/30/0	-	-		
ESD	E2	ESD CDM	-	500 Volts	-	-	-		1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	-		1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	-	-		1/3/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-		3/90/0

QBS: Qual By Similarity
Qual Device TPS54260DGQR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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